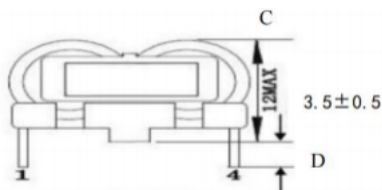
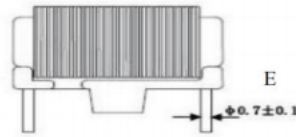


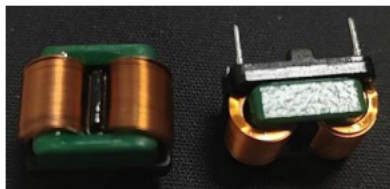
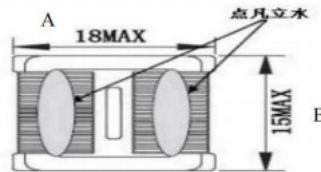
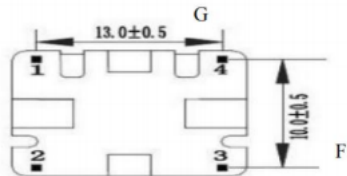
DIMENSION:(UNIT:mm)



正视图



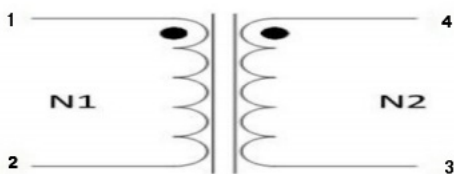
侧视图



A	18.0 MAX
B	15.0 MAX
C	12.0 MAX
D	3.5±0.5
E	0.7±0.1
F	10.0±0.5
G	13.0±0.5

AC 1000V	COIL-COIL
AC 500V	COIL-CORE

SCHEMATICS:



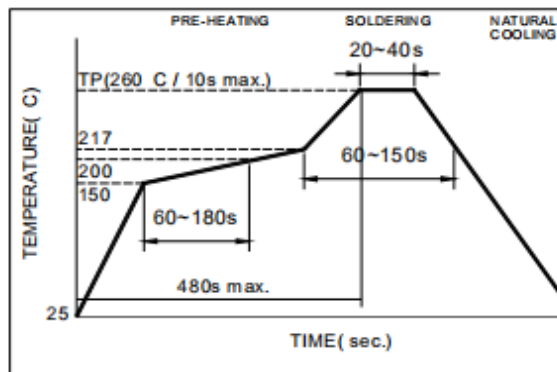
ELECTRONICAL CHARACTERISTIC		
ITEM	SPEC.	TEST FRE.
L	20mH MIN	1KHZ/0.25V
RDC	160m Ω MAX	25℃
IDC	1.2~2.1A	1KHZ/0.25V
	ΔT≤40℃ TYP	1KHZ/0.25V
Test Internal Resistance 20 Ω		

MAIN MATERIALS LIST:

NO	DESCRIPTION	MATERIAL
1	MIRE	SFT-UEWJ180°C 0.13*1.0*46 TS(REF)
2	DR CORE	Mn-Zn Painting
3	RI CORE	无
4	BASE/CLIP	T375HF 150 C
5	EPOXY	无

SOLDERING CONDITIONS

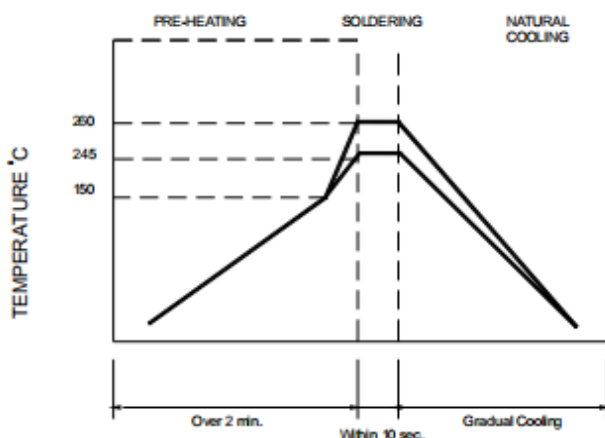
**Figure 1.
Re-flow
Soldering (Lead
Free)**



Note:

- Preheat circuit and products to 150°C
- 260°C tip temperature (max)
- Reflow times: no more than 2 times
- Solder paste thickness: the best 0.08mm is, but max is 0.1mm

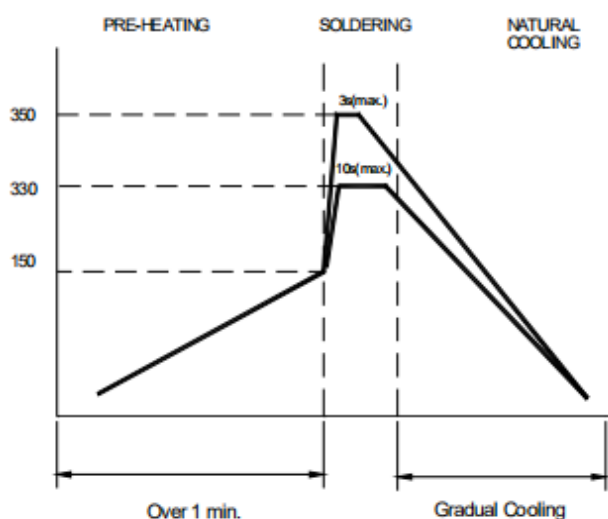
**Figure 2.
Wave Soldering**



Note :

- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)

**Figure 3.
Hand Soldering**



Note:

- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 3 sec.